



### MATERIAL DATA FORM

#### Manufacturer contact Information

Contact Name	<a href="#">Compliance Coordinator</a>
Tel. No.	+1 (805) 377-3648
E-mail address	<a href="mailto:Compliance@diodes.com">Compliance@diodes.com</a>

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
MBR20xxCTP	1.31	Die,Schottky	Doped silicon	TBD	6.2014	0.47%	4724
Customer's Partnumber.		ITO220Sleadframe	KFC(PMC 90)	TBD	365.6400	27.86%	278552
			Die attached pad plating	TBD	0.5758	0.04%	439
		Heatsink	6063 Alloy	TBD	432.0540	32.91%	329148
		Bonding wire	Aluminum	TBD	7.1106	0.54%	5417
		Molding compound	CEL-3650	TBD	489.0210	37.25%	372546
		High temperature solder	PbSnAg Alloy	TBD	5.0909	0.39%	3878
		Tin solder	Pure Tin	37508652	6.9516	0.53%	5296

Total (mg)	1312.645
------------	----------



### MATERIAL DATA FORM

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight		
MBR20xxCTP	1.313	Die,Schottky	Doped silicon	Si	7440-21-3	6.2014	100.00%	1000000	4724		
Customer's Partnumber.		ITO220Sleadframe	KFC(PMC90)	Fe	1309-37-1	0.3656	0.10%	1000	279		
				P	7723-14-0	0.1097	0.03%	300	84		
			Pure Nickel	Cu	7440-50-8	365.1647	99.87%	998700	278190		
				Ni	7440-02-0	0.5758	100.00%	1000000	439		
		Heatsink	6063 Alloy	Si	7440-21-3	1.7282	0.40%	4000	1317		
						Fe	1309-37-1	1.5122	0.35%	3500	1152
						Cu	7440-50-8	0.4321	0.10%	1000	329
						Mn	7439-96-5	0.4321	0.10%	1000	329
						Mg	7439-95-4	3.0244	0.70%	7000	2304
						Cr (Not CrVI)	7440-47-3	0.4321	0.10%	1000	329
						Zn	7440-66-6	0.4321	0.10%	1000	329
						Ti	7440-32-6	0.4321	0.10%	1000	329
		Bonding wire	20 mil	Al	7429-90-5	7.1106	100.00%	1000000	5417		
		Molding compound	CEL-3650	Epoxy Resin	-----	53.7923	11.00%	110000	40980		
						Phenol Resin	-----	24.4511	5.00%	50000	18627
						Carbon black	1309-64-4	0.9780	0.20%	2000	745
						Sb2O3	1309-64-4	4.8902	1.00%	10000	3725
						Brominated Epox	40039-93-8	14.6706	3.00%	30000	11176
		High temperature solder	Pb5Sn2.5Ag	Silica	14808-60-7	390.2388	79.80%	798000	297292		
						Pb	7439-92-1	4.7091	92.50%	925000	3587
						Ag	7440-22-4	0.1273	2.50%	25000	97
		Tin solder	Pure Tin	Sn	7440-31-5	0.2545	5.00%	50000	194		
				Sn	7440-31-5	6.9516	100.00%	1000000	5296		
<b>Total (mg)</b>						<b>1312.645</b>					

MATERIALS DISCLOSURE DISCLAIMER	
<p>1. The materials are disclosed according to JIG-101 "Material Composition Declaration for Electronic Products"</p> <p>2. Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee its completeness and accuracy due to the fact that the data has been compiled based on information provided by our subcontractors and raw material suppliers. Complete information may not have been provided to protect their business proprietary information. Based on the above considerations this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components.</p> <p>3. These estimates do not include trace levels of dopants and metal materials within the silicon devices contained inside of the finished products.</p>	
<p>This product or product family does not contain any of the following substances except as <b>CURRENTLY</b> exempted by ELVII and RoHS and reported above:</p>	
<p>1. Asbestos</p> <p>2. Azo compounds</p> <p>3. Cadmium and cadmium compounds</p> <p>4. Certain Shortchain Chlorinated Paraffins</p> <p>5. Chlorinated organic compounds</p> <p>6. Hexavalent chromium compounds</p> <p>7. Lead and lead compounds</p> <p>8. Mercury and mercury compounds</p> <p>9. Organic tin compounds</p> <p>10. Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)</p>	<p>11. Ozone Depleting Substances - Class II (HCFCs)</p> <p>12. Perfluorooctane Sulphonate (PFOS) or related compounds</p> <p>13. Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including <b>DecaBDE</b></p> <p>14. Polychlorinated Biphenyls (PCBs)</p> <p>15. Polychlorinated Naphthalenes (&gt;3 chlorine atoms)</p> <p>16. Radioactive Substances</p> <p>17. Tributyl Tin (TBT) and Triphenyl Tin (TPT)</p> <p>18. Tributyl Tin Oxide (TBTO)</p>
<p>This product or product family meet REACH requirements for chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHC) appended below:</p>	
<p>1. Anthracene</p> <p>2. 4,4'- Diaminodiphenylmethane</p> <p>3. Dibutyl phthalate (DBP)</p> <p>4. Cyclododecane</p> <p>5. Cobalt dichloride</p> <p>6. Diarsenic pentaoxide</p> <p>7. Diarsenic trioxide</p> <p>8. Sodium dichromate, dihydrate</p>	<p>9. Bis (2-ethyl(hexyl)phthalate) (DEHP)</p> <p>10. Hexabromocyclododecane (HBCDD)</p> <p>11. Bis(tributyltin)oxide (TBTO)</p> <p>12. Lead hydrogen arsenate</p> <p>13. Triethyl arsenate</p> <p>14. Benzyl butyl phthalate (BBP)</p> <p>15. 5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)</p> <p>16. Alkanes, C10-13, chloro (SCCPs - Short Chain Chlorinated Paraffins)</p>